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STPS30L40CG/CT/CW

LOW DROP POWER SCHOTTKY RECTIFIER

MAIN PRODUCTS CHARACTERISTICS

I_{F(AV)}	2 x 15 A
V_{RRM}	40 V
T_{j (max)}	150 °C
V_{F (max)}	0.50 V

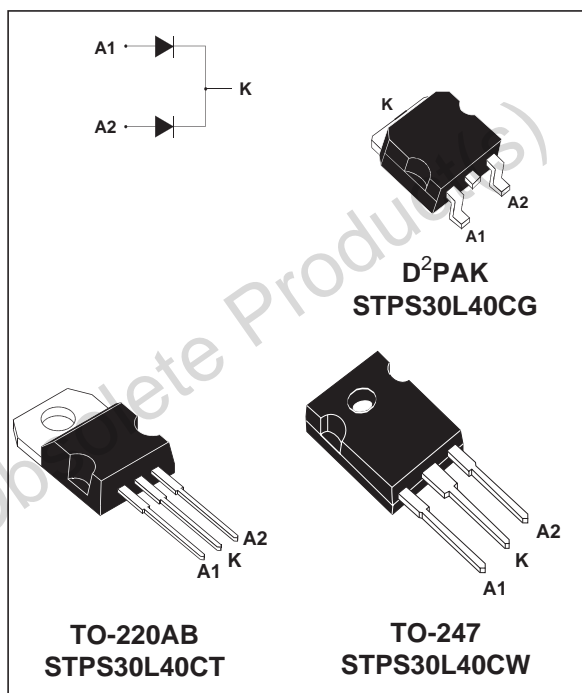
FEATURES AND BENEFITS

- VERY SMALL CONDUCTION LOSSES
- NEGLIGIBLE SWITCHING LOSSES
- LOW FORWARD VOLTAGE DROP
- LOW THERMAL RESISTANCE
- AVALANCHE CAPABILITY SPECIFIED

DESCRIPTION

Dual center tap schottky rectifiers suited for Switched Mode Power Supplies and high frequency DC to DC converters.

Packaged in TO-247, TO-220AB and D²PAK these devices are intended for use in low voltage, high frequency inverters, free-wheeling and polarity protection applications.



ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter		Value	Unit
V _{RRM}	Repetitive peak reverse voltage		40	V
I _{F(RMS)}	RMS forward current		30	A
I _{F(AV)}	Average forward current	T _c = 135°C δ = 0.5	Per diode 30 Per device	A
I _{FSM}	Surge non repetitive forward current	tp = 10 ms Sinusoidal	220	A
I _{RRM}	Repetitive peak reverse current	tp = 2 μs square F=1kHz	1	A
I _{RSM}	Non repetitive peak reverse current	tp = 100 μs square	3	A
P _{ARM}	Repetitive peak avalanche power	tp = 1 μs T _j = 25°C	6000	W
T _{stg}	Storage temperature range		- 65 to + 150	°C
T _j	Maximum operating junction temperature *		150	°C
dV/dt	Critical rate of rise of reverse voltage		10000	V/μs

* : $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th}(j-a)}$ thermal runaway condition for a diode on its own heatsink

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THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
R _{th(j-c)}	Junction to case	Per diode	1.60	°C/W
		Total	0.85	
R _{th(c)}		Coupling	0.10	°C/W

When the diodes 1 and 2 are used simultaneously :
 $\Delta T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$

STATIC ELECTRICAL CHARACTERISTICS (per diode)

Symbol	Parameter	Tests Conditions		Min.	Typ.	Max.	Unit	
I _R *	Reverse leakage current	T _j = 25°C	V _R = V _{RRM}			360	μA	
		T _j = 100°C			20	50	mA	
V _F *	Forward voltage drop	T _j = 25°C	I _F = 15 A			0.55	V	
		T _j = 125°C			0.42	0.50		
		T _j = 25°C		I _F = 30 A				0.74
		T _j = 125°C				0.59		0.67

Pulse test : * tp = 380 μs, δ < 2%

To evaluate the conduction losses use the following equation :
 $P = 0.330 \times I_{F(AV)} + 0.011 I_{F(RMS)}^2$

Fig. 1: Average forward power dissipation versus average forward current (per diode).

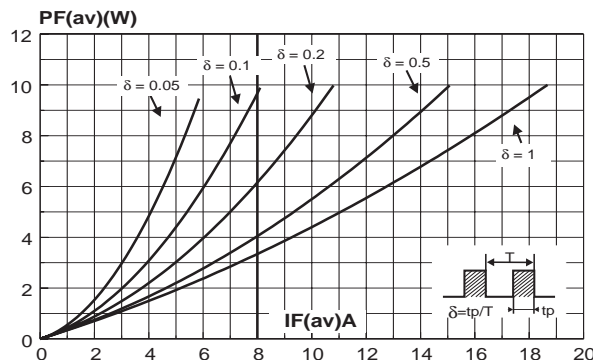
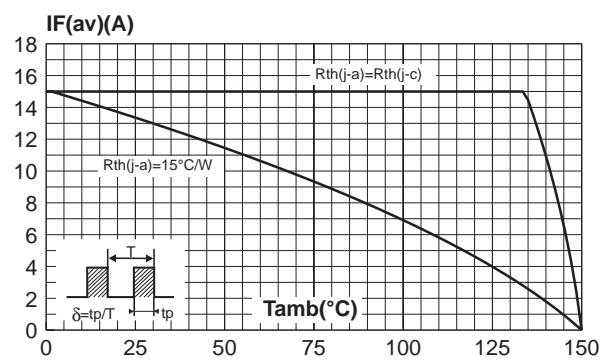


Fig. 2: Average current versus ambient temperature (δ=0.5) (per diode).



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Fig. 3: Normalized avalanche power derating versus pulse duration.

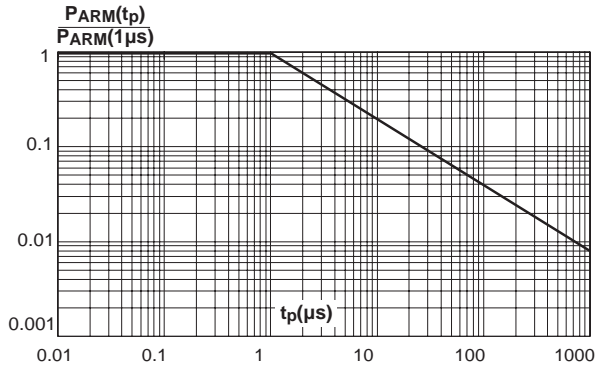


Fig. 4: Normalized avalanche power derating versus junction temperature.

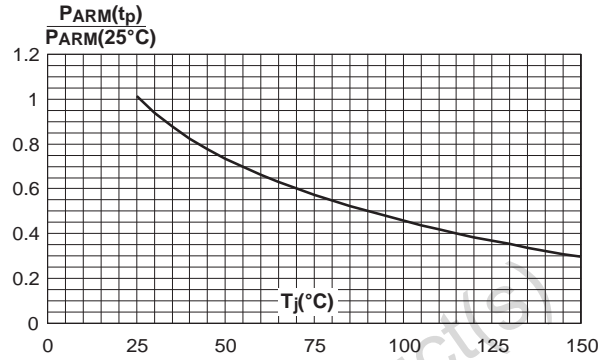


Fig. 5: Non repetitive surge peak forward current versus overload duration (maximum values) (per diode).

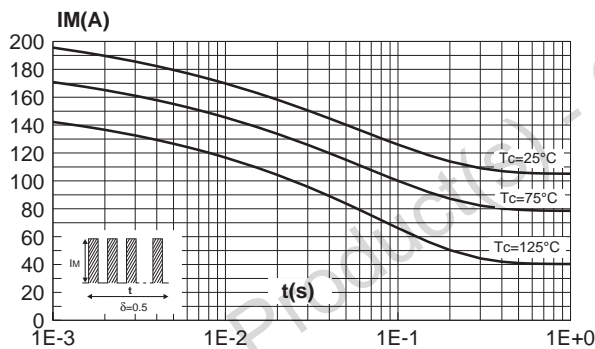


Fig. 6: Relative variation of thermal transient impedance junction to case versus pulse duration.

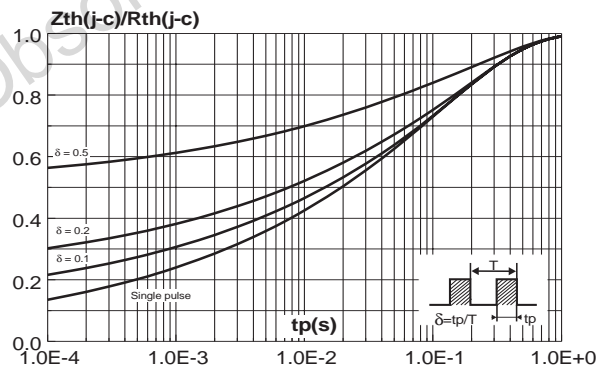


Fig. 7: Reverse leakage current versus reverse voltage applied (typical values) (per diode).

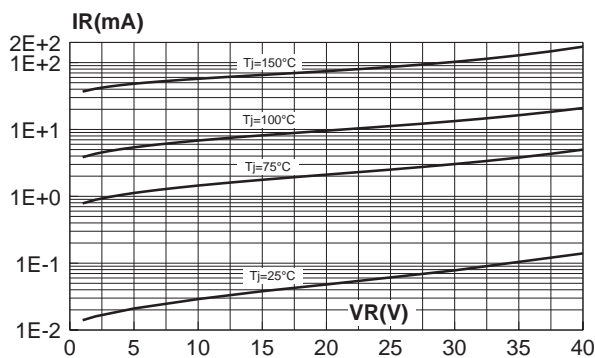
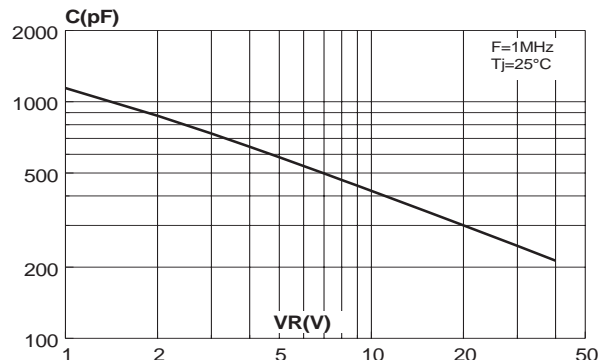


Fig. 8: Junction capacitance versus reverse voltage applied (typical values) (per diode).



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Fig. 9: Forward voltage drop versus forward current (maximum values) (per diode).

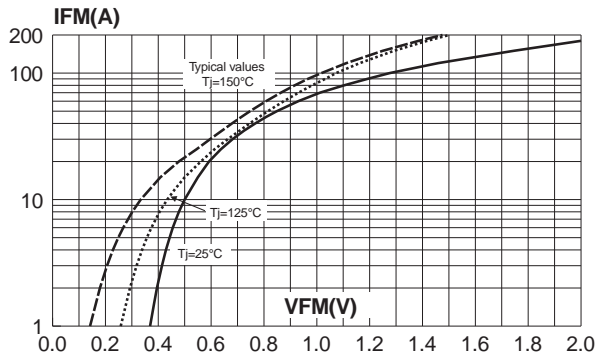
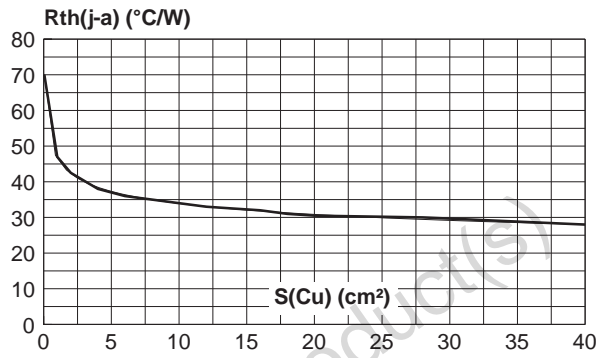
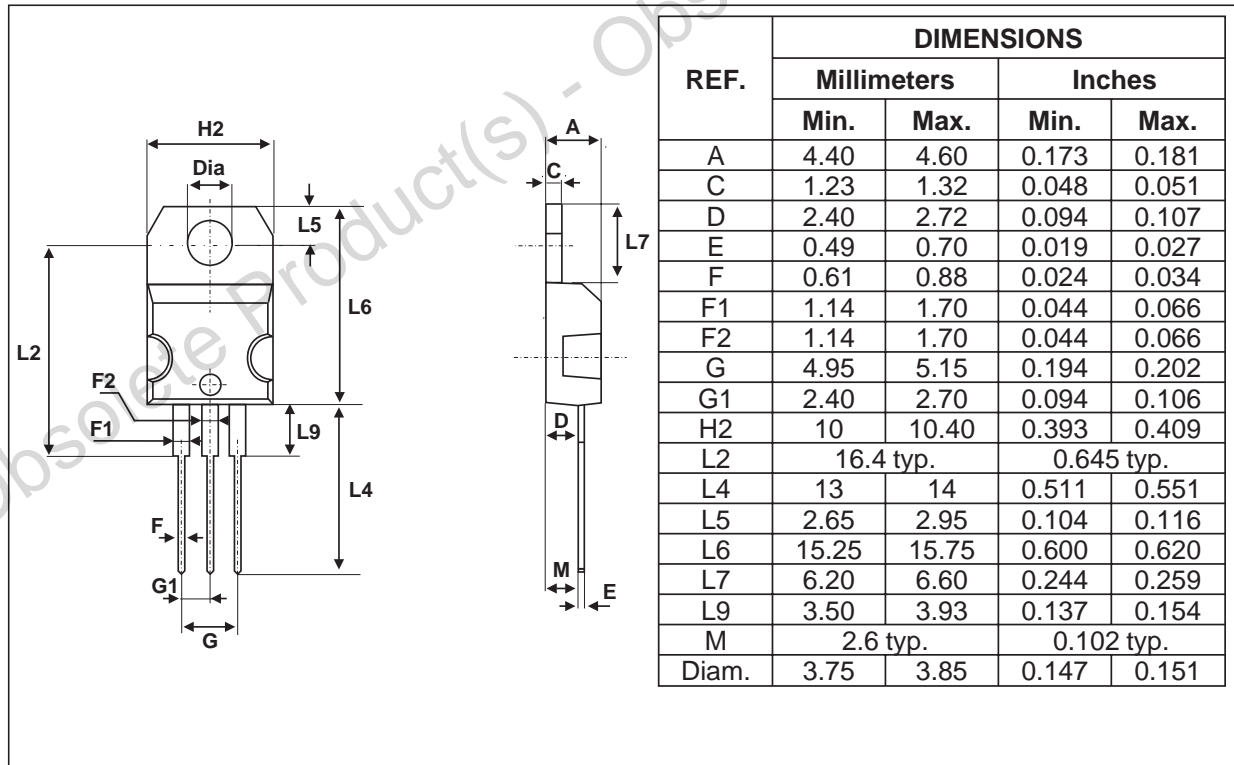


Fig. 10: Thermal resistance junction to ambient versus copper surface under tab (Epoxy printed circuit board FR4, copper thickness: 35µm) (STPS30L40CG only).



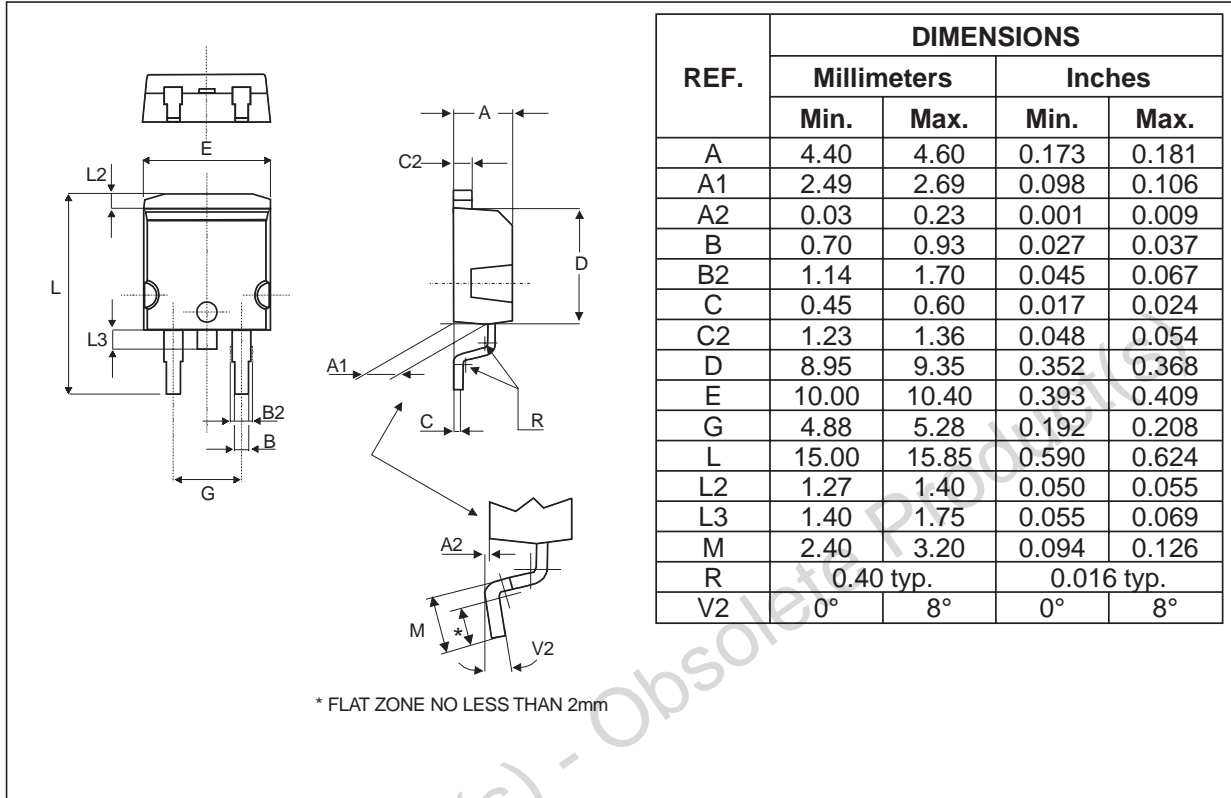
PACKAGE MECHANICAL DATA
TO-220AB



- COOLING METHOD : C
- RECOMMENDED TORQUE VALUE : 0.55 M.N
- MAXIMUM TORQUE VALUE : 0.70 M.N

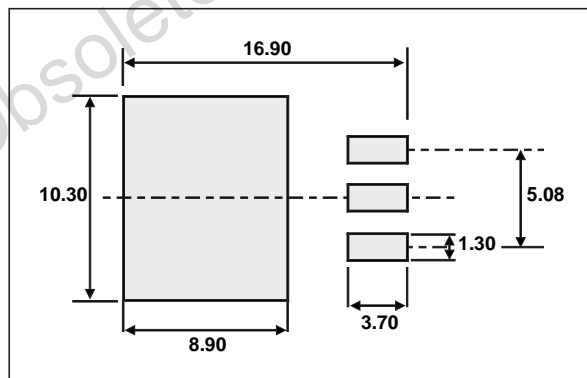
STPS30L40CG/CT/CW

PACKAGE MECHANICAL DATA
D²PAK



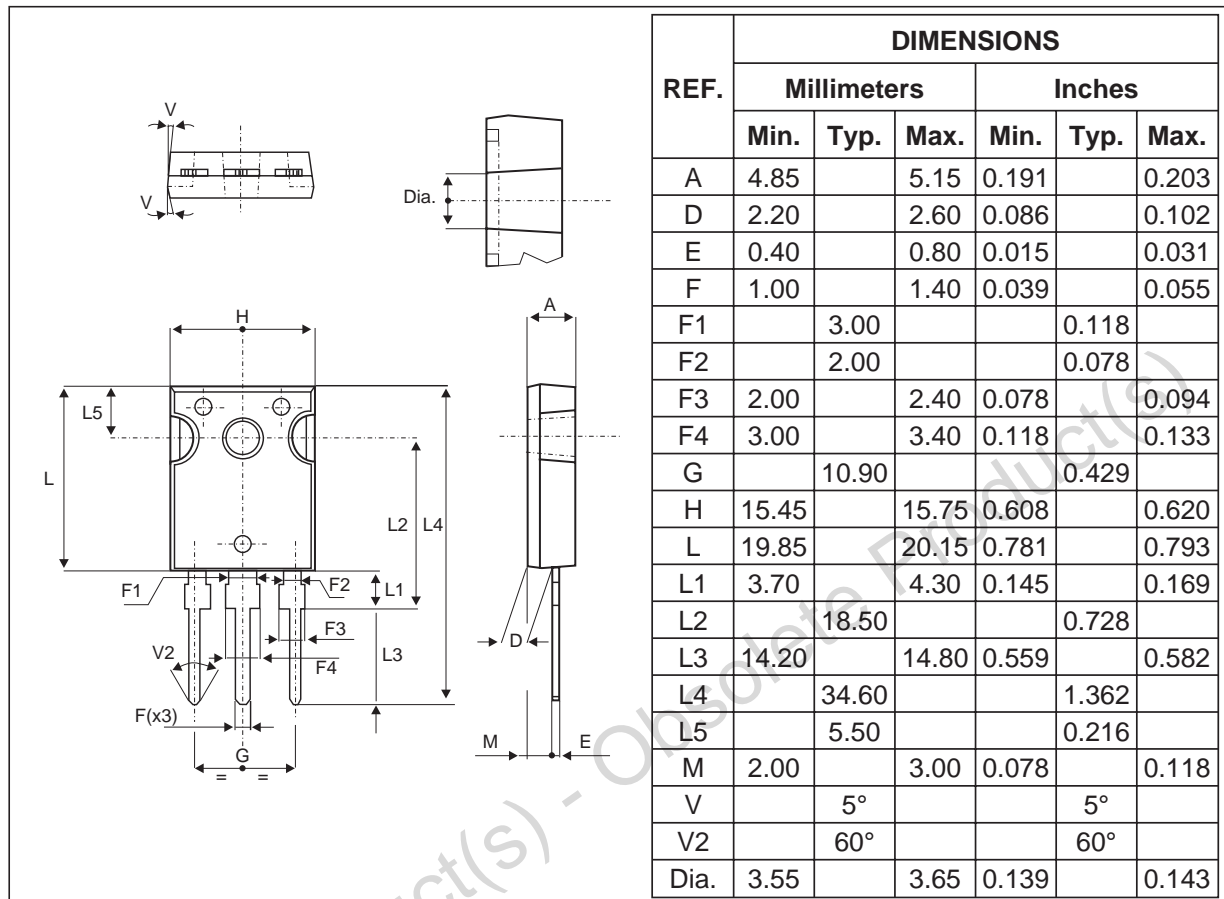
- COOLING METHOD : BY CONDUCTION (METHOD C)

FOOT PRINT (in millimeters)
D²PAK



STPS30L40CG/CT/CW
PACKAGE MECHANICAL DATA

TO-247



- COOLING METHOD : C
- RECOMMENDED TORQUE VALUE : 0.8M.N
- MAXIMUM TORQUE VALUE : 1.0M.N

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS30L40CT	STPS30L40CT	TO-220AB	2g	50	Tube
STPS30L40CG	STPS30L40CG	D ² PAK	1.8g	50	Tube
STPS30L40CG-TR	STPS30L40CG	D ² PAK	1.8g	500	Tape & reel
STPS30L40CW	STPS30L40CW	TO-247	4.4g	30	Tube

- EPOXY MEETS UL94,V0

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